

IEEE P802.3df Task Force – Electrical Ad hoc

18 April 2022 Ad hoc Electronic Teleconference Meeting

Approved Meeting Minutes, Prepared by Kent Lusted

Meeting called to order at 7:02 am (all times Pacific) by Kent Lusted, who was chairing the meeting.

Chair noted that individuals should fill out IMAT information for attendance.

Presentation #1 Agenda and General Information

Presenter: Kent Lusted

URL

https://www.ieee802.org/3/df/public/adhoc/electrical/22_0418/agenda_3df_adhoc_220418.pdf

The chair asked if there were any modifications for the agenda (See slide #2) – there were none.

There were no other objections to the approval of the agenda, and it was considered approved by unanimous consent.

The chair noted an email had been sent out to the reflector reminding individuals to review the following IEEE SA policies-

- IEEE SA Participation Policy
- IEEE SA Copyright Policy
- IEEE SA Patent Policy

Chair asked if anyone needed any of these policies reviewed in-depth. There were no requests.

Chair presented the third slide (See Slide #22) of the IEEE SA Patent Policy slides. Chair did call for Potentially Essential Patents, and no one came forward.

Chair presented the second slide (See Slide #27) of the IEEE SA Copyright Policy slides. Chair noted – “By participating in this activity, you agree to comply with the IEEE Code of Ethics, all applicable laws, and all IEEE policies and procedures including, but not limited to, the IEEE SA Copyright Policy.”

Chair presented the second slide (See Slide #31) of the IEEE SA Participation Policy slides. Chair noted – “Participants in the IEEE-SA “individual process” shall act independently of others, including employers. By participating in standards activities using the “individual process”, you are deemed to accept these requirements; if you are unable to satisfy these requirements then you shall immediately cease any participation.”

The chair reviewed meeting decorum. See Slide #3.

The chair reviewed voting. No motions, other than approval of agenda and minutes, will be heard. Anyone who feels qualified can vote in a straw poll.

Chair noted that he received updated presentations from Chris Diminico and Adee Ran. The Diminico contribution had editorial changes. (see:

https://www.ieee802.org/3/df/public/adhoc/electrical/22_0418/diminico_3df_elec_01a_220418.pdf) The Ran

contribution had editorial changes and a new slide 12. (see:

https://www.ieee802.org/3/df/public/adhoc/electrical/22_0418/ran_3df_elec_01a_220418.pdf) Chair asked if there was objection to hearing the updated presentations. No one responded.

Presentation #2 802.3df 800GBASE-CR8 Annex 162C/162D Table Revisions

Presenter Chris Diminico

URL https://www.ieee802.org/3/df/public/adhoc/electrical/22_0418/diminico_3df_elec_01a_220418.pdf

Presentation #2 **200G/lane Electrical interfaces - system implications**
 Presenter Adee Ran
 URL https://www.ieee802.org/3/df/public/adhoc/electrical/22_0418/ran_3df_elec_01a_220418.pdf

Straw Poll #1:

I am interested in C2M AUIs that would support the following form factors:

- a. PCB host front panel pluggable
- b. cabled-host front panel pluggable
- c. co-package
- d. near-package

(chicago rules)

Results: A: 50, B: 47, C: 38, D: 38

Chair reviewed future meetings.

Meeting adjourned at ~8:59 am Pacific.

Attendees (per IMAT)

Name	Employer	Affiliation
Akinwale, Oluwafemi		Intel Corporation
Ben-Artzi, Liav	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
Ben-Hamida, Naim		Ciena Corporation
Bernier, Eric		Huawei Technologies Canada; Huawei Technologies Co., Ltd
Bois, Karl	NVIDIA Corporation	NVIDIA Corporation
Brown, Matthew	Huawei Technologies Canada	Huawei Technologies Canada
Bruckman, Leon	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Choe, Denz		BeCe Pte Ltd
D'Ambrosia, John	Futurewei Technologies	Futurewei Technologies, U.S. Subsidiary of Huawei
Dawe, Piers J G	NVIDIA	Nvidia
Diminico, Christopher	M C Communications, LLC	Panduit Corp.
Dudek, Michael	Marvell	Marvell
Ewen, John	Marvell	Marvell
FILIPPOU, DIMITRIS		Dimitris Filippou; I2QS

Gao, Xiangrong	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Geng, Limin	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Ghiasi, Ali	Ghiasi Quantum LLC	Ghiasi Quantum LLC; Marvell Semiconductor, Inc.
Gustlin, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
Han, Ruibo	China Mobile Communications Corporation (CMCC)	China Mobile Communications Corporation (CMCC)
Haser, Alexandra	Molex Incorporated	Molex Incorporated
He, Xiang	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Heck, Howard	Intel Corporation	Intel Corporation
Hidaka, Yasuo	Credo Semiconductor	Credo Semiconductor
Huang, Kechao		Huawei Technologies Co., Ltd
Kabra, Lokesh	Synopsys, Inc.	Synopsys, Inc.
Kim, Kihong/Joshua	Hirose Electric (USA), Inc.	Hirose Electric (USA), Inc.
Klempa, Michael	University of New Hampshire InterOperability Laboratory (UNH-IOL)	Amphenol Corporation
Kondo, Taiji	MegaChips Corporation	Dexerials Corporation
Li, Mike-Peng	Intel Corporation	Intel Corporation
Li, Pei-Rong	MediaTek Inc.	MediaTek Inc.
Lusted, Kent	Intel Corporation	Intel Corporation
Maki, Jeffery	Juniper Networks, Inc.	Juniper Networks, Inc.
Malicoat, David	Malicoat Networking Solutions	Malicoat Networking Solutions; SENKO Advanced Components
Mellitz, Richard	Samtec, Inc.	Samtec, Inc.
Meltser, Roman		NVIDIA Corporation
Moorwood, Charles	Keysight Technologies	Keysight Technologies
Mu, Jianwei		Hisense
Murty, Ramana	Broadcom Inc.	Broadcom Corporation
Nering, Raymond	Cisco Systems, Inc.	Cisco Systems, Inc.
Ofelt, David	Juniper Networks, Inc.	Juniper Networks, Inc.
Opsasnick, Eugene	Broadcom Inc.	Broadcom Inc.
Palkert, Thomas	Macom, Samtec	Samtec-Macom
PARK, CHUL SOO	Juniper Networks Inc.	Juniper Networks, Inc.
Rabinovich, Rick	Keysight Technologies	Keysight Technologies
Radhamohan, Rajeshmohan	Cisco Systems, Inc.	Cisco Systems, Inc.
Ran, Adee	Cisco Systems, Inc.	Cisco Systems, Inc.
Ren, Hao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Rodes, Roberto	II-VI	II-VI
Sakai, Toshiaki	Socionext Inc.	socionext
Simms, William	NVIDIA Corporation	NVIDIA Corporation
Slavick, Jeff	Broadcom Inc	Broadcom Inc
Sommers, Scott	Molex LLC	Molex Incorporated

Son, Yung Sung	Optomind Inc	Optomind Inc
Sorbara, Massimo	GLOBALFOUNDRIES	GLOBALFOUNDRIES
SU, CHANGZHENG		Huawei Technologies Co., Ltd
Sun, Yi		OFS
Tailor, Bharat	Semtech Canada Corporation	Semtech Canada Corporation
Torza, Anthony		Cisco Systems, Inc.
Tran, Viet	Keysight Technologies	Keysight Technologies
Ulrichs, Ed	Intel Corporation	Intel Corporation
Wang, Haojie	China Mobile Communications Corporation (CMCC)	China Mobile Communications Corporation (CMCC)
Wang, Ruoxu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Wang, Xinyuan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Whiteman, Cameron	Infinera Corporation	Infinera Corporation
Wu, Mau-Lin	MediaTek Inc.	MediaTek Inc.
Yin, Shuang		Google
Zhiwei, Yang	ZTE Corporation	ZTE Corporation
Zhuang, Yan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd